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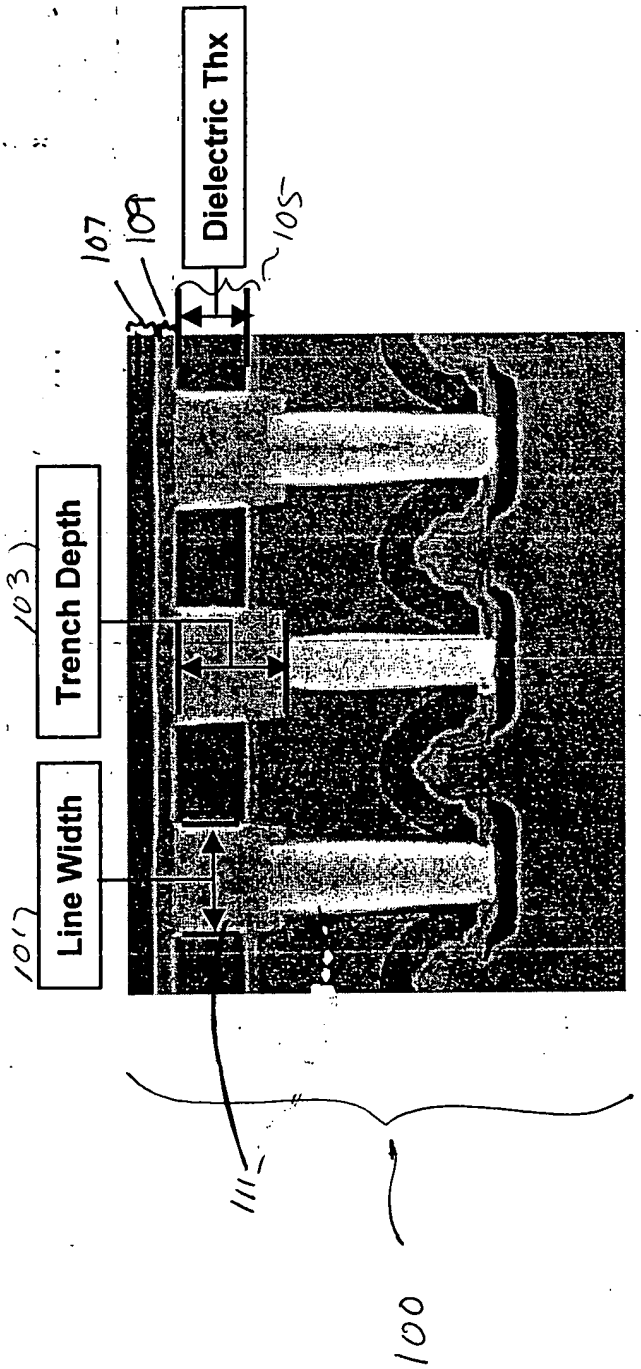

FIG. 1

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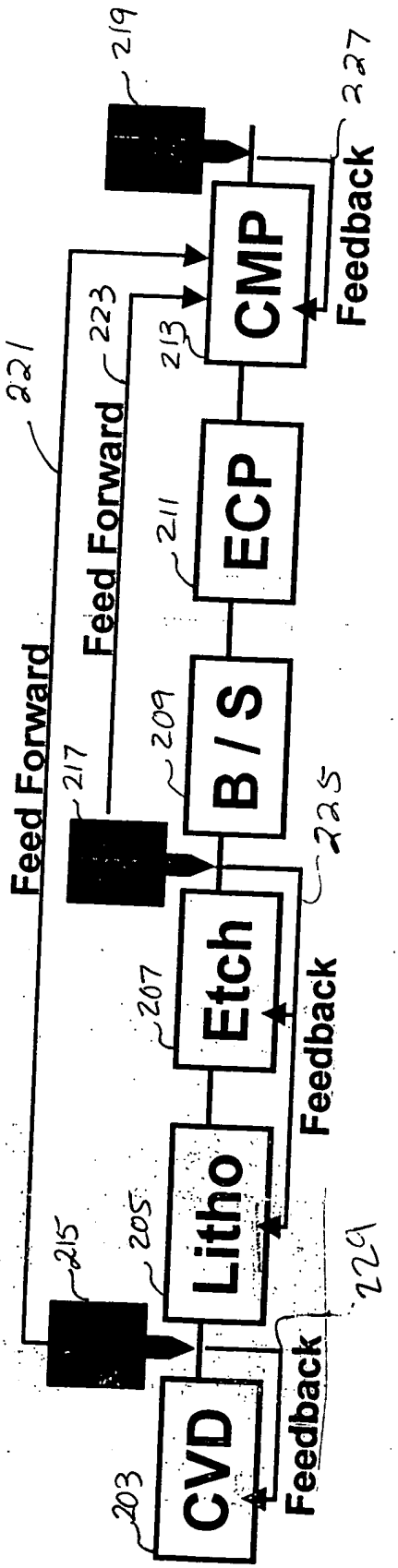

FIG. 2

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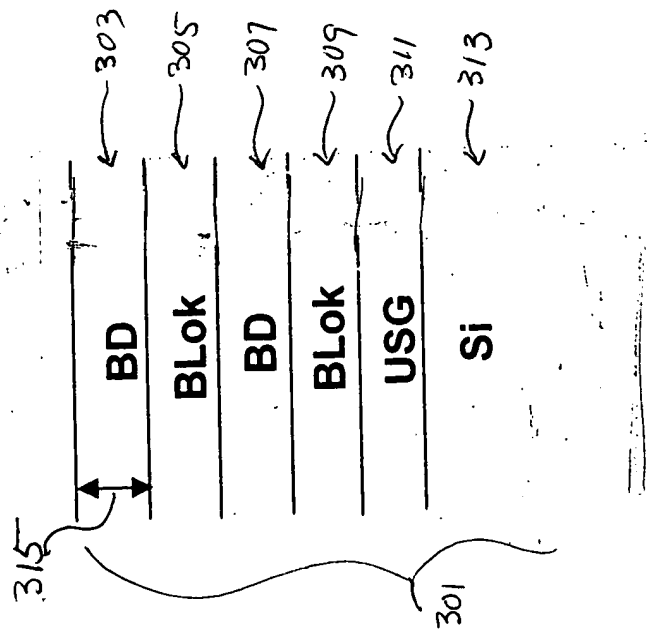


FIG. 3

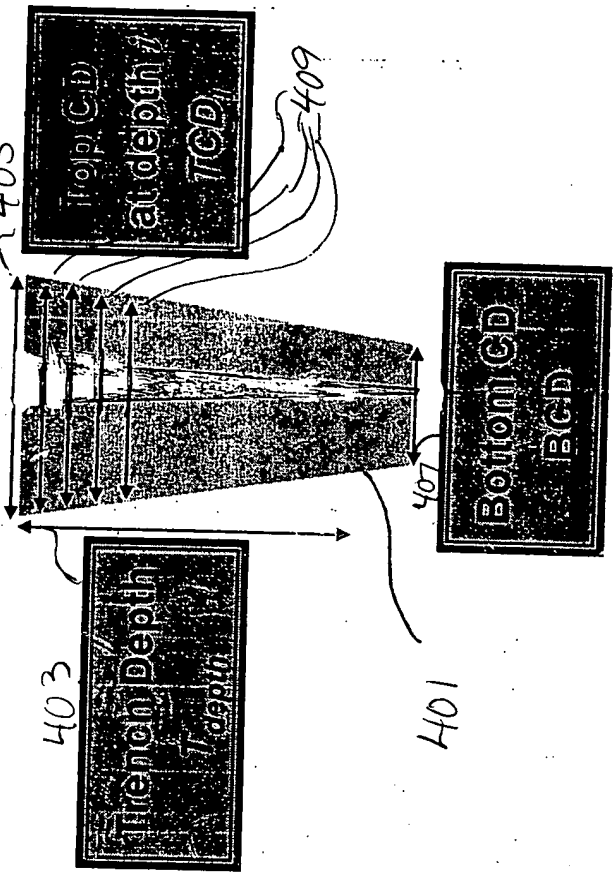
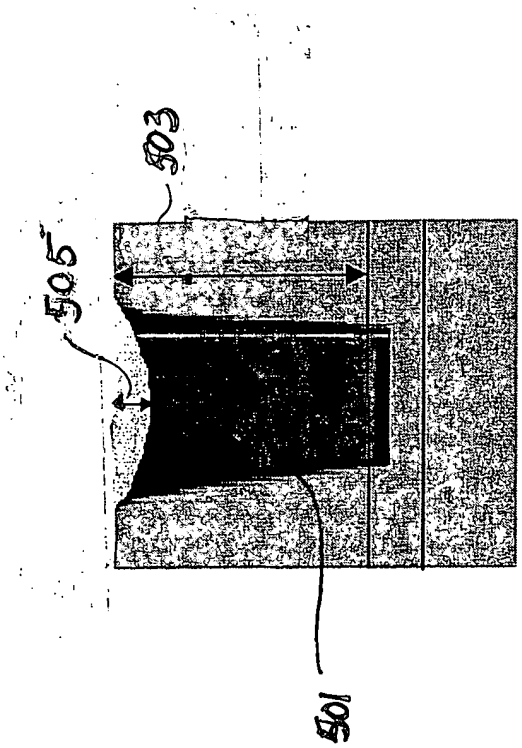


FIG. 4

BEST AVAILABLE COPY

FIG. 5



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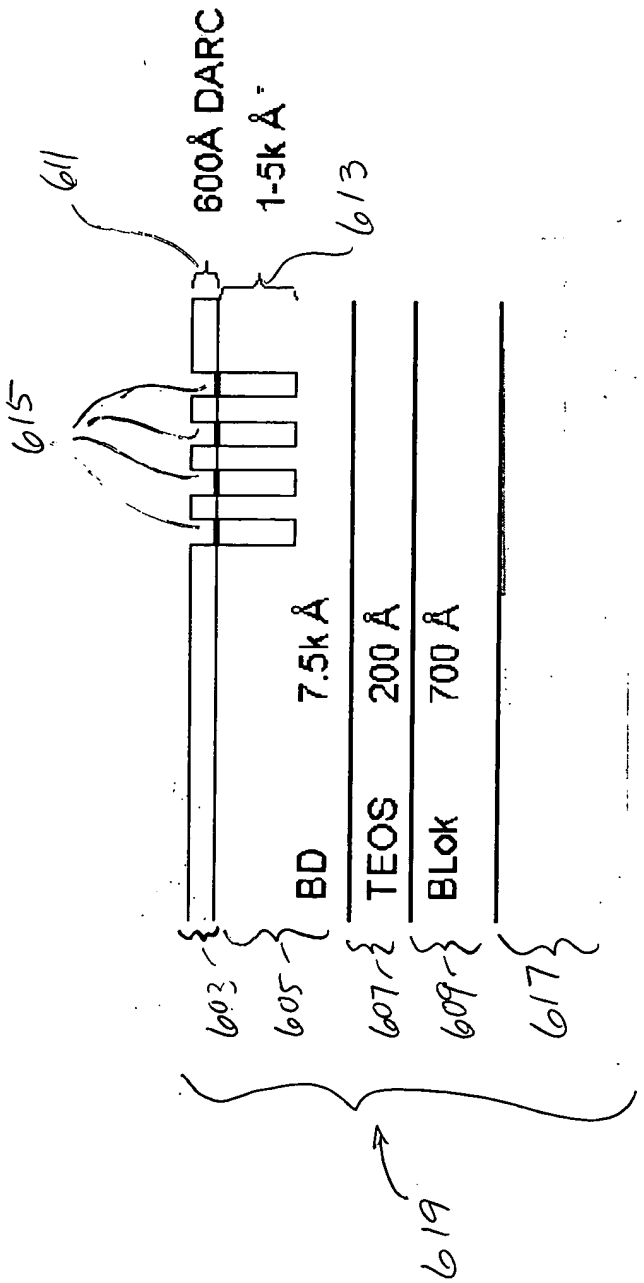

FIG. 6

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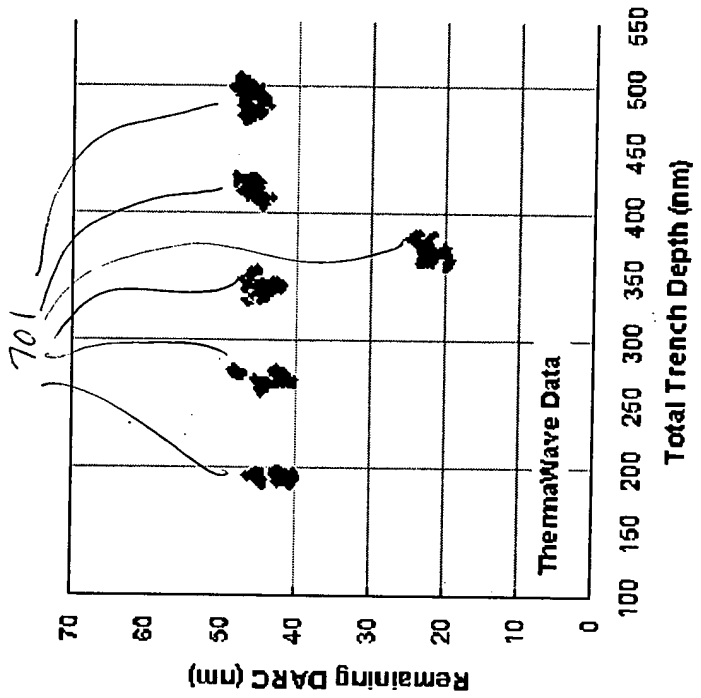
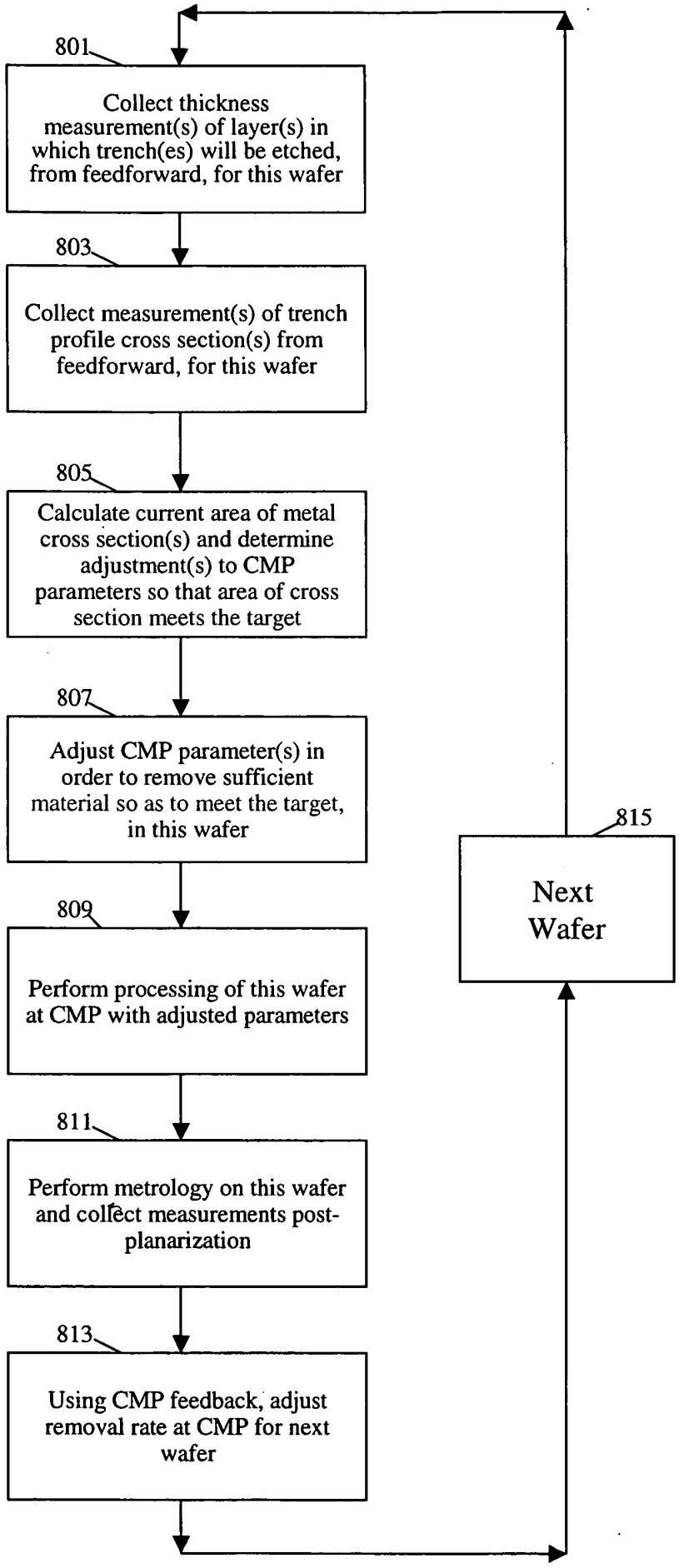


FIG. 7

Figure 8


801
Collect thickness measurement(s) of layer(s) in which trench(es) will be etched, from feedforward, for this wafer
803
Collect measurement(s) of trench profile cross section(s) from feedforward, for this wafer
805
Calculate current area of metal cross section(s) and determine adjustment(s) to CMP parameters so that area of cross section meets the target
807
Adjust CMP parameter(s) in order to remove sufficient material so as to meet the target, in this wafer
809
Perform processing of this wafer at CMP with adjusted parameters
811
Perform metrology on this wafer and collect measurements post-planarization
813
Using CMP feedback, adjust removal rate at CMP for next wafer
815
Next Wafer

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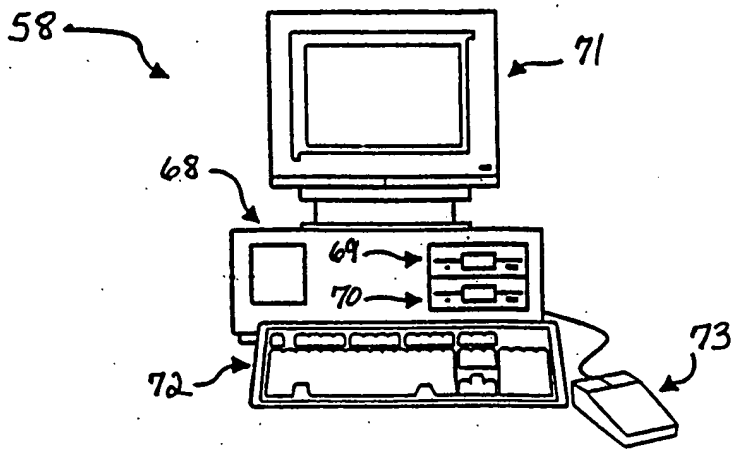

FIG. 9

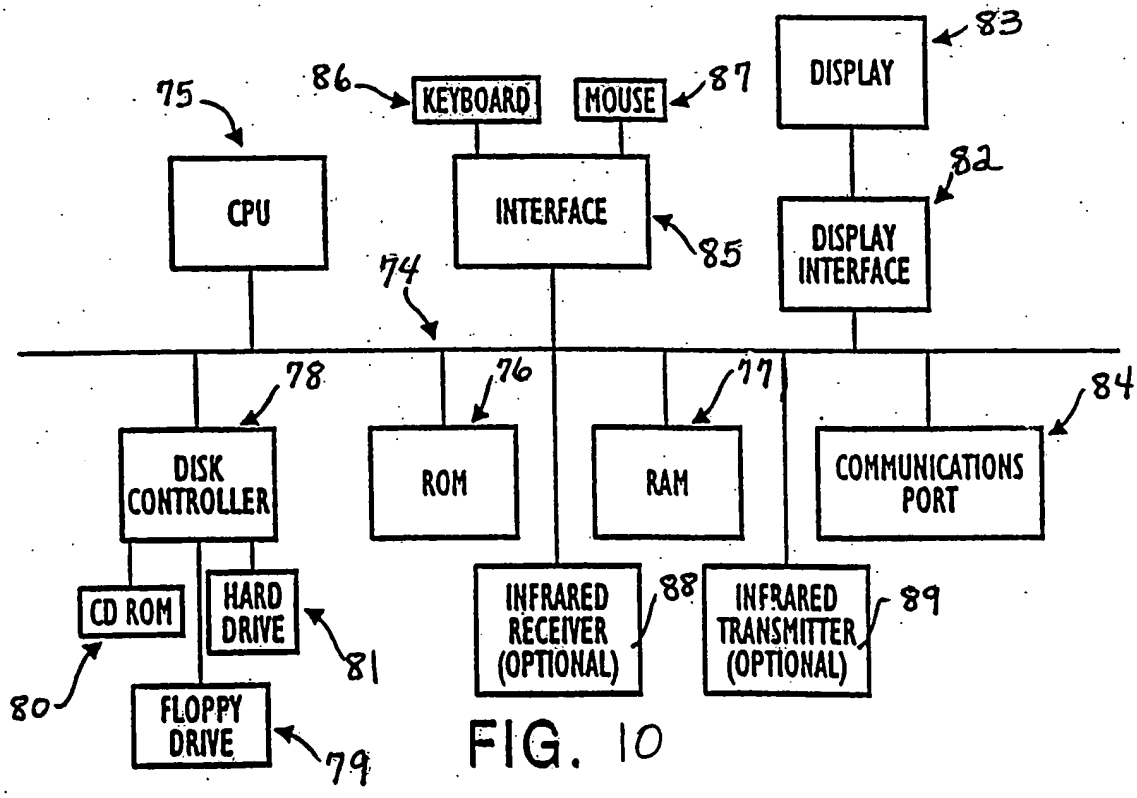

FIG. 10